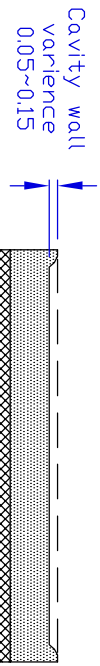
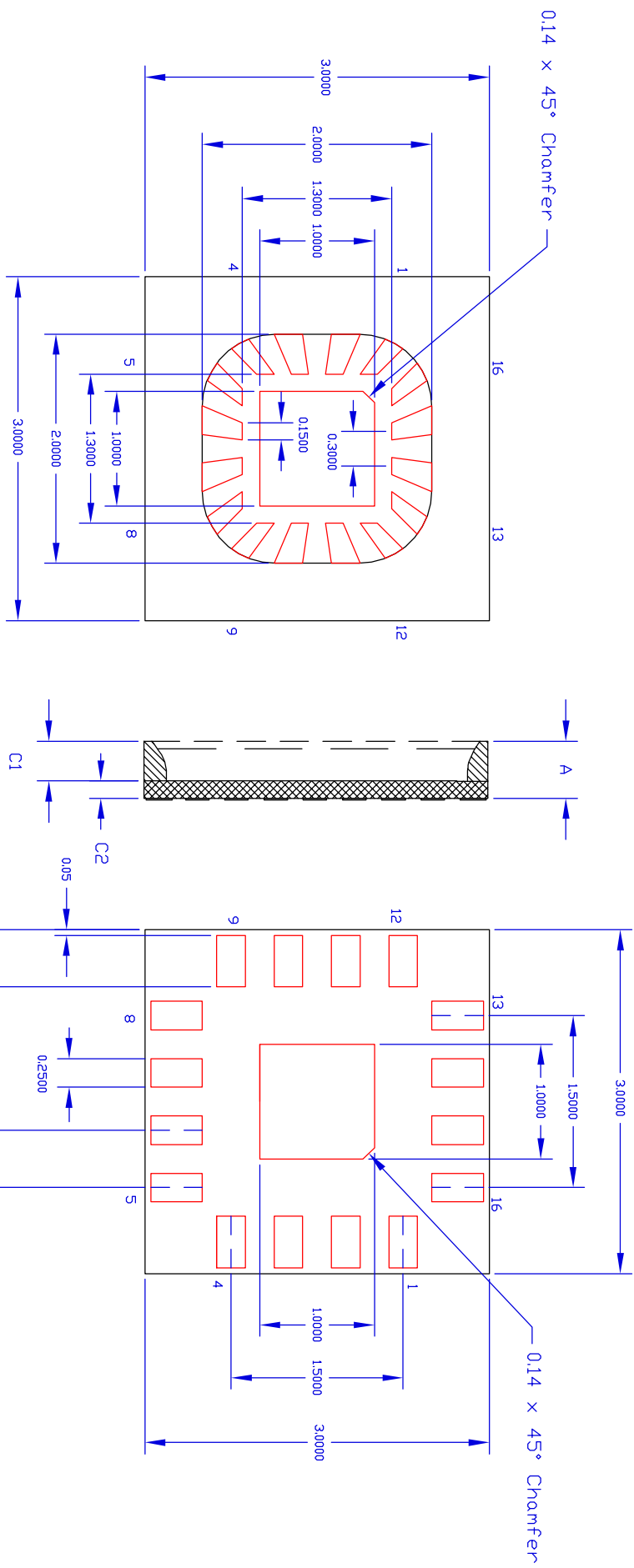


TOP VIEW SIDE VIEW BOTTOM VIEW



SIDE VIEW

HEIGHT TABLE			
SERIES	C1	C2	A
A-QFN	0.63	0.27	0.90
A-TQFN	0.38	0.27	0.65
TDL	+/-	+/- 0.10	+/- 0.05
			+/- 0.15

OTHER SIZES AVAILABLE

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TOLERANCES UNLESS NOTED:		APPROVALS		DATE					
X.XXX	±	ENG	TA	11/29/08	TITLE 16-LEAD 3MM P=0.50MM A-QFN (AIR) OPEN CAVITY				
X.XXX	±	DRAWN		MFG		SCALE	SIZE	DRAWING NO.	REV
X.XXX	±	CUST		REVISED		NONE	A	451610	A
ANGLES	±	DO NOT SCALE DRAWING		SHEET		1 OF		1	

- Note:
- Organic substrate
 - Cavity Dam: Hysol FP4451TD
 - Pads: Cu/Ni/Au
 - Copper Thickness: 12µm~18µm (0.5~0.7mil)
 - Bonding Pad Gold Thickness: 1.3µm (50 micro-inch)
 - PCB Pads Gold Thickness: 0.13µm (5 micro-inch)
 - Nickel Thickness: 3.8µm (150 micro-inch)
 - All Dimensions Are mm